

L Number	Hits	Search Text	DB	Time stamp
1	816192	bond\$3	USPAT; US-PGPUB; JPO	2003/09/08 09:31
2	202412	wafer\$1	USPAT; US-PGPUB; JPO	2003/09/08 09:31
3	280	thined or thining	USPAT; US-PGPUB; JPO	2003/09/08 09:31
4	311456	etch\$3	USPAT; US-PGPUB; JPO	2003/09/08 09:31
5	8467	bond\$3 near3 wafer\$1	USPAT; US-PGPUB; JPO	2003/09/08 09:32
6	34897	(thined or thining) or thinning	USPAT; US-PGPUB; JPO	2003/09/08 09:33
7	933	((thined or thining) or thinning) and (bond\$3 near3 wafer\$1)	USPAT; US-PGPUB; JPO	2003/09/08 09:33
8	840	etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3 wafer\$1))	USPAT; US-PGPUB; JPO	2003/09/08 09:33
9	462143	copper or cu	USPAT; US-PGPUB; JPO	2003/09/08 09:34
10	829	(etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3 wafer\$1))) and "10"	USPAT; US-PGPUB; JPO	2003/09/08 09:34
11	237	(etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3 wafer\$1))) and (copper or cu)	USPAT; US-PGPUB; JPO	2003/09/08 09:34
12	696	(((thined or thining) or thinning) and (bond\$3 near3 wafer\$1)) not (((etch\$3 and (((thined or thining) or thinning) and (bond\$3 near3 wafer\$1))) and (copper or cu)))	USPAT; US-PGPUB; JPO	2003/09/08 09:34